# TOSHIBA

Unit: mm

TOSHIBA Power Transistor Module Silicon NPN Epitaxial Type (Four Darlington Power Transistors in One)

# MP4104

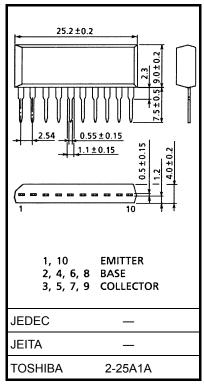
#### High Power Switching Applications

Hammer Drive, Pulse Motor Drive and Inductive Load Switching

- Small package by full molding (SIP 10 pins)
- High collector power dissipation (4-device operation) :  $P_T = 4 W (Ta = 25^{\circ}C)$
- High collector current: IC (DC) = 4 A (max)
- High DC current gain:  $h_{FE} = 2000 \text{ (min)} (V_{CE} = 2 \text{ V}, I_C = 1.5 \text{ A})$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Collector-base voltage		V <sub>CBO</sub>	120	V	
Collector-emitter voltage		V <sub>CEO</sub>	100	V	
Emitter-base voltage		V <sub>EBO</sub>	6	V	
Collector current	DC	ΙC	4	A	
	Pulse	I <sub>CP</sub>	6		
Continuous base current		Ι <sub>Β</sub>	0.5	А	
Collector power dissipation		Pc	2.0	W	
(1-device operation)					
Collector power dissipation		Рт	4.0	W	
(4-device operation)			4.0		
Junction temperature		Tj	150	°C	
Storage temperature range		T <sub>stg</sub>	−55 to 150	°C	

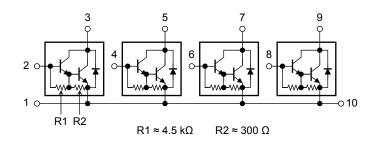


Weight: 2.1 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

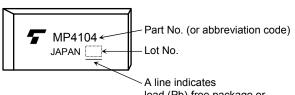
### **Array Configuration**



Industrial Applications

# **TOSHIBA**

## Marking



lead (Pb)-free package or lead (Pb)-free finish.

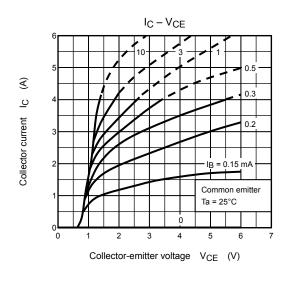
## **Thermal Characteristics**

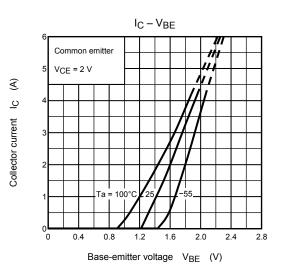
Characteristics	Symbol	Max	Unit	
Thermal resistance from junction to ambient	ΣR <sub>th (j-a)</sub>	31.3	°C/W	
(4-device operation, $Ta = 25^{\circ}C$ )	· · · ·			
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)				

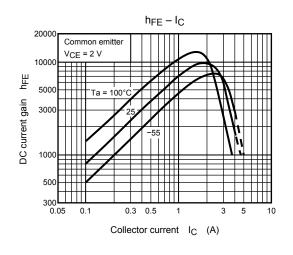
## Electrical Characteristics (Ta = 25°C)

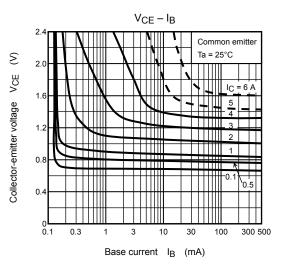
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Collector cut-off current		I <sub>CBO</sub>	V <sub>CB</sub> = 120 V, I <sub>E</sub> = 0 A	_	_	10	μA	
Collector cut-off current		ICEO	V <sub>CE</sub> = 100 V, I <sub>B</sub> = 0 A	_		10	μA	
Emitter cut-off current		I <sub>EBO</sub>	V <sub>EB</sub> = 6 V, I <sub>C</sub> = 0 A	0.5		2.5	mA	
Collector-base breakdown voltage		V (BR) CBO	I <sub>C</sub> = 1 mA, I <sub>E</sub> = 0 A	120	_	_	V	
Collector-emitter breakdown voltage		V (BR) CEO	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0 A	100		_	V	
DC current gain		h <sub>FE (1)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 1.5 A	2000	_	15000		
		h <sub>FE (2)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 3.0 A	1000		_		
Saturation voltage	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = 1.5 A, I <sub>B</sub> = 3 mA	_		1.5	v	
	Base-emitter	V <sub>BE (sat)</sub>	I <sub>C</sub> = 1.5 A, I <sub>B</sub> = 3 mA	_	_	2.0		
Transition frequency		fT	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 0.5 A	_	60	_	MHz	
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	30	_	pF	
Switching time	Turn-on time	ton	$Input   B1  20 µs   B2  M = V CC = 30 V I_{B1} = -I_{B2} = 3 mA$	_	0.3	_		
	Storage time	t <sub>stg</sub>			2.0	_	μs	
	Fall time	t <sub>f</sub>		_	0.4	_		

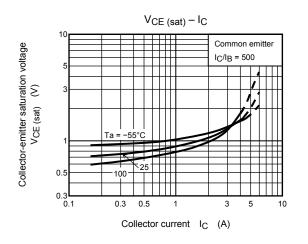
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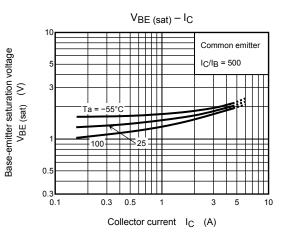


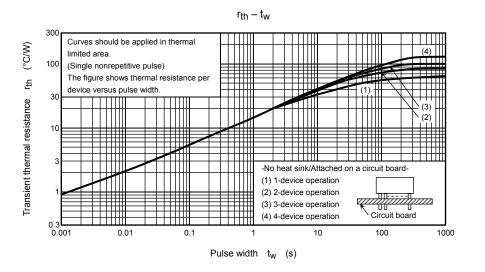


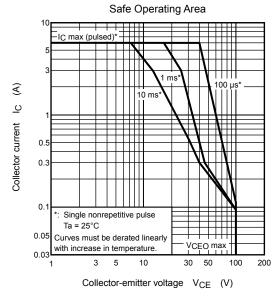




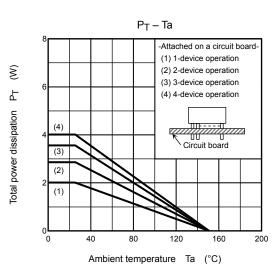








 $\Delta T_j - P_T$ 160 (°C/W) (1) (2) . (3) (4) 120 £ Transient thermal resistance 80 Ŵ ťΰ Circuit board -Circuit board-(1) 1-device operation (2) 2-device operation (3) 3-device operation (4) 4-device operation 1 2 3 4 5 Total power dissipation PT (W)



#### **RESTRICTIONS ON PRODUCT USE**

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